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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL N°/IM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10062650	01/31/2002	438		2812	2825 LUU CHUON

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****CONTINUING DATA VERIFIED:**

**** FOREIGN APPLICATIONS VERIFIED:**

PG-PUB ☐ DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no
35 USC 119 conditions met ☐ yes ☐ no
Verified and Acknowledged Examiners's Initials *

ATTORNEY DOCKET NO

36080.01101

TITLE : Encapsulated integrated circuit package and method of manufacturing an integrated circuit package

U.S. DEPT. OF COMM./PAT. & TM-PTO-438 (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	
ISSUE FEE			
Amount Due	Date Paid	Amount Due	
<input type="checkbox"/> TERMINAL		Application Examiner	
DISCLAIMER		PREPARED FOR ISSUE	
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